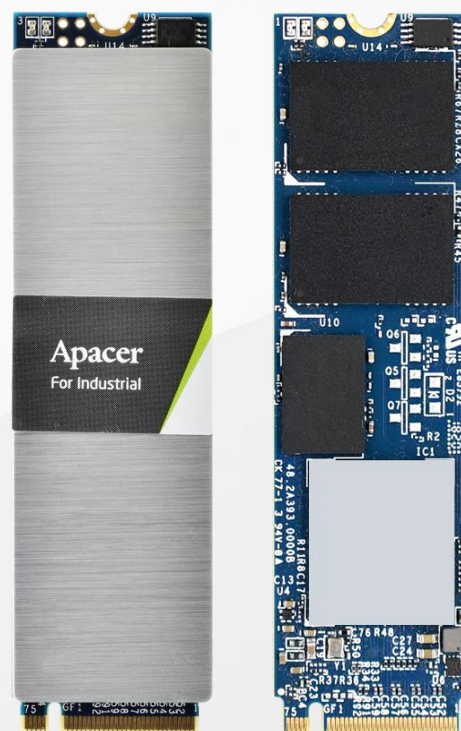


## RoHS Compliant PCI Express Flash Drive

### PV310-M280 Product Specifications



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Version 1.9



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## Specifications Overview:

- **PCIe Interface**
  - Compliant with PCIe Express 3.1
  - Compliant with NVMe 1.3
  - Compatible with PCIe Gen3 x4 interface
- **Capacity**
  - 240, 480, 960 GB
- **Performance\***
  - Interface burst read/write: 4 GB/sec
  - Sequential read: up to 2,660 MB/sec
  - Sequential write: up to 2,260 MB/sec
  - Random read (4K): up to 345,000 IOPS
  - Random write (4K): up to 172,000 IOPS
- **Flash Management**
  - Low-Density Parity-Check (LDPC) Code
  - Global Wear Leveling
  - Flash bad-block management
  - Flash Translation Layer: Page Mapping
  - S.M.A.R.T.
  - Power Failure Management
  - TRIM
  - Hyper Cache Technology
  - Over-Provisioning
  - DataRAID™
  - NVMe Secure Erase
- **DRAM Cache for Enhanced Random Performance**
- **Security**
  - End-to-End Data Protection
  - AES 256-bit hardware encryption
  - Trusted Computing Group (TCG) Opal 2.0 (optional)
- **Endurance (in drive writes per day : DWPD)**
  - 240 GB: 3.91 DWPD
  - 480 GB: 3.88 DWPD
  - 960 GB: 3.37 DWPD
- **Temperature Range**
  - Operating:
    - Standard: 0°C to 70°C
    - Wide: -40°C to 85°C
  - Storage: -40°C to 100°C
- **Supply Voltage**
  - 3.3 V ± 5%
- **Power Consumption\***
  - Active mode: 1,725 mA
  - Idle mode: 250 mA
- **Connector Type**
  - 75-pin M.2 module pinout
- **Power Management**
  - Supports APST
  - Supports ASPM L1.2
- **Form Factor**
  - Form Factor: M.2 2280
  - Dimensions:
    - Standard temp.: 80.00 x 22.00 x 3.88, unit: mm
    - Wide temp.: 80.00 x 19.85 x 4.58, unit: mm
  - Net Weight:
    - Standard temp.: 7.92 g ± 5%
    - Wide temp.: 10.10 g ± 5%
- **NAND Flash Type: 3D TLC (BiCS3)**
- **MTBF: >3,000,000 hours**
- **Shock & Vibration\*\***
  - Shock: 1,500 G
  - Vibration: 15 G
- **Reliability**
  - Thermal Sensor
  - Thermal Management Technique
  - CoreGlacier™\*\*\*
- **LED Indicators for Drive Behavior**
- **RoHS Compliant**

\*Varies from capacities. The values for performances and power consumptions presented are typical and may vary depending on flash configurations or platform settings.

\*\*Non-operating

\*\*\*Only supported on wide temperature series

## Table of Contents

<b>1. General Descriptions .....</b>	<b>4</b>
<b>2. Functional Block .....</b>	<b>4</b>
<b>3. Pin Assignments.....</b>	<b>5</b>
<b>4. Product Specifications.....</b>	<b>7</b>
4.1 Capacity.....	7
4.2 Performance .....	7
4.3 Environmental Specifications .....	7
4.4 Mean Time Between Failures (MTBF) .....	8
4.5 Certification and Compliance.....	8
4.6 Endurance .....	8
4.7 LED Indicator Behavior.....	9
<b>5. Flash Management .....</b>	<b>10</b>
5.1 Error Correction/Detection.....	10
5.2 Bad Block Management .....	10
5.3 Global Wear Leveling .....	10
5.4 Power Failure Management .....	10
5.5 Flash Translation Layer – Page Mapping.....	11
5.6 TRIM.....	11
5.7 Hyper Cache Technology .....	11
5.8 Over-Provisioning .....	11
5.9 DataRAID™ .....	11
5.10 NVMe Secure Erase.....	11
<b>6. Security &amp; Reliability Features .....</b>	<b>12</b>
6.1 Thermal Sensor .....	12
6.2 Thermal Management Technique .....	12
6.3 End-to-End Data Protection.....	12
6.4 Advanced Encryption Standard.....	12
6.5 TCG Opal (optional) .....	13
6.6 CoreGlacier™ .....	13
<b>7. Software Interface .....</b>	<b>14</b>
7.1 Command Set.....	14

7.2 S.M.A.R.T. .... 15

**8. Electrical Specifications.....17**

8.1 Operating Voltage..... 17

8.2 Power Consumption ..... 17

**9. Physical Characteristics.....18**

9.1 Standard Temperature ..... 18

9.2 Wide Temperature..... 18

9.3 Net Weight..... 19

**10. Product Ordering Information.....20**

10.1 Product Code Designations..... 20

10.2 Valid Combinations..... 21

## 1. General Descriptions

Apacer PV310-M280 is the fastest SSD designed as M.2 2280 mechanical dimensions, providing full compliance with PCIe Gen3 x4 interface and NVMe 1.3 specifications. Built with a powerful PCIe controller, PV310-M280 delivers outstanding performance in data transfer, reaching up to 345,000/172,000 and 2,660/2,260 MB/s in IOPS and sequential read/write.

In terms of security, Advanced Encryption Standard (AES) and Trusted Computing Group (TCG) Opal ensure data security and provide users with a peace of mind knowing their data is safeguarded against unauthorized use at all times. Furthermore, with End-to-End Data Protection, data integrity can be assured at multiple points in the path to enable reliable delivery of data transfers.

## 2. Functional Block

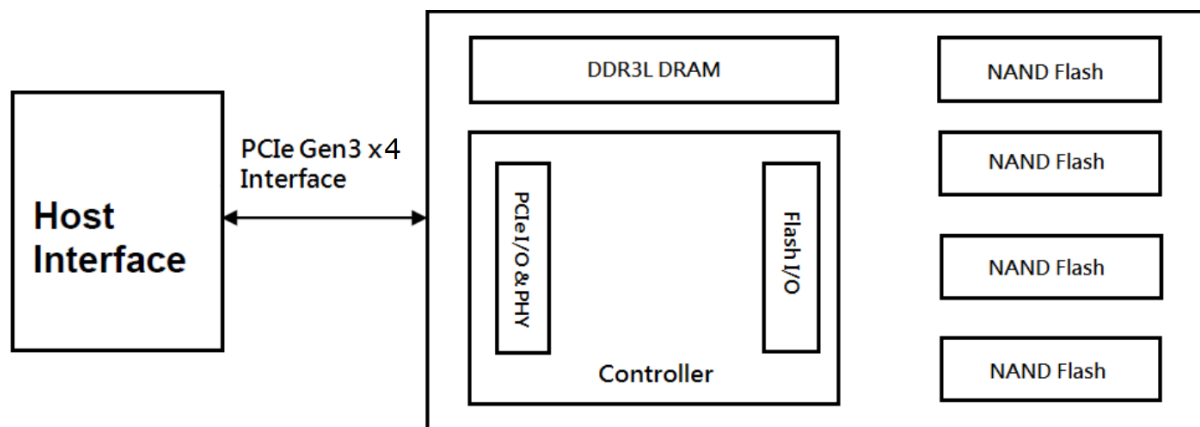


Figure 2-1 Functional Block Diagram

### 3. Pin Assignments

This connector does not support hot plug capability. There are a total of 75 pins. 12 pin locations are used for mechanical key locations; this allows such a module to plug into Key M connectors.

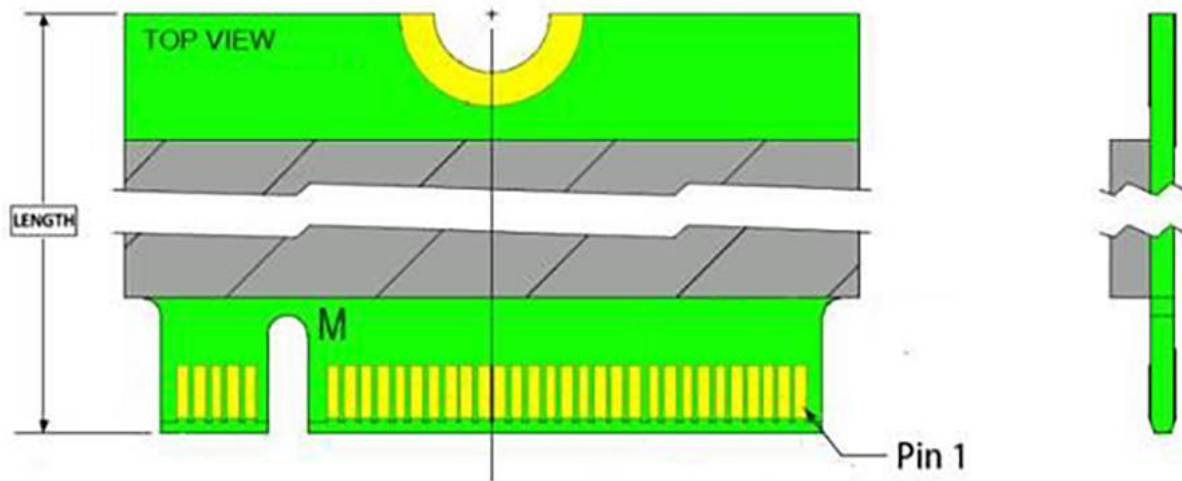


Table 3-1 Pin Assignments

Pin	Type	Description
1	GND	Ground
2	3.3V	3.3V source
3	GND	Ground
4	3.3V	3.3V source
5	PETn3	PCIe TX Differential signal defined by the PCI Express M.2 spec
6	N/C	No connect
7	PETp3	PCIe TX Differential signal defined by the PCI Express M.2 spec
8	N/C	No connect
9	GND	Ground
10	LED1#(O)	Status indicators via LED devices
11	PERn3	PCIe RX Differential signal defined by the PCI Express M.2 spec
12	3.3V	3.3V source
13	PERp3	PCIe RX Differential signals defined by the PCI Express M.2 spec
14	3.3V	3.3V source
15	GND	Ground
16	3.3V	3.3V source
17	PETn2	PCIe TX Differential signal defined by the PCI Express M.2 spec
18	3.3V	3.3V source
19	PETp2	PCIe TX Differential signal defined by the PCI Express M.2 spec
20	N/C	No connect
21	GND	Ground
22	N/C	No connect
23	PERn2	PCIe RX Differential signal defined by the PCI Express M.2 spec
24	N/C	No connect
25	PERp2	PCIe RX Differential signal defined by the PCI Express M.2 spec
26	N/C	No connect
27	GND	Ground
28	N/C	No connect
29	PETn1	PCIe TX Differential signal defined by the PCI Express M.2 spec
30	N/C	No connect
31	PETp1	PCIe TX Differential signal defined by the PCI Express M.2 spec
32	N/C	No connect

**Table 3-1 Pin Assignments**

Pin	Type	Description
33	GND	Ground
34	N/C	No connect
35	PERn1	PCIe RX Differential signal defined by the PCI Express M.2 spec
36	N/C	No connect
37	PERp1	PCIe RX Differential signal defined by the PCI Express M.2 spec
38	N/C	No connect
39	GND	Ground
40	SMB_CLK	SMBus clock; Open Drain with pull up on platform
41	PETn0	PCIe TX Differential signal defined by the PCI Express M.2 spec
42	SMB_DATA	SMBus Data; Open Drain with pull up on platform
43	PETp0	PCIe TX Differential signal defined by the PCI Express M.2 spec
44	ALERT#	Alert notification to host system. Open Drain with pull up on platform, Active low Signals
45	GND	Ground
46	N/C	No connect
47	PERn0	PCIe RX Differential signal defined by the PCI Express M.2 spec
48	N/C	No connect
49	PERp0	PCIe RX Differential signal defined by the PCI Express M.2 spec
50	PERST#(I/O)(0/3.3V)	PE-Reset is a functional reset to the card as specification. defined by the PCIe Mini CEM
51	GND	Ground
52	CLKREQ#(I/O)(0/3.3V)	Clock Request is a reference clock request signal as defined by the PCIe Mini CEM specification; Also used by L1 PM Substates.
53	REFCLKn	PCIe Reference Clock signals (100 MHz) spec. defined by the PCI Express M.2
54	PEWAKE#(I/O)(0/3.3V)	Open Drain with pull up on platform; Active Low. PCIe PME Wake.
55	REFCLKp	PCIe Reference Clock signals (100 MHz) spec. defined by the PCI Express M.2
56	Reserved for MFG DATA	Manufacturing Data line. Used for SSD manufacturing only. Not used in normal operation. Pins should be left N/C in platform Socket.
57	GND	Ground
58	Reserved for MFG CLOCK	Manufacturing Clock line. Used for SSD manufacturing only. Not used in normal operation. Pins should be left N/C in platform Socket.
59	Module Key	Module Key
60	Module Key	Module Key
61	Module Key	Module Key
62	Module Key	Module Key
63	Module Key	Module Key
64	Module Key	Module Key
65	Module Key	Module Key
66	Module Key	Module Key
67	N/C	No connect
68	SUSCLK(32KHz) (I/O)(0/3.3V)	32.768 kHz clock supply input that is provided by the platform chipset to reduce power and cost for the module.
69	PEDET (NC-PCIe)	Host I/F Indication; No Connect for PCIe.
70	3.3V	3.3V source
71	GND	Ground
72	3.3V	3.3V source
73	GND	Ground
74	3.3V	3.3V source
75	GND	Ground

## 4. Product Specifications

### 4.1 Capacity

Capacity specifications of PV310-M280 are available as shown in Table 4-1. It lists the specific capacity and the default numbers of heads, sectors and cylinders for each product line.

**Table 4-1** Capacity Specifications

Capacity	Total bytes*	Total LBA
240 GB	240,057,409,536	468,862,128
480 GB	480,103,981,056	937,703,088
960 GB	960,197,124,096	1,875,385,008

\*Display of total bytes varies from file systems, which means not all of the bytes can be used for storage.

\*\*Notes: 1 GB = 1,000,000,000 bytes; 1 sector = 512 bytes.

LBA count addressed in the table above indicates total user storage capacity and will remain the same throughout the lifespan of the device. However, the total usable capacity of the SSD is most likely to be less than the total physical capacity because a small portion of the capacity is reserved for device maintenance usages.

### 4.2 Performance

Performance of PV310-M280 is listed below in Table 4-2.

**Table 4-2** Performance Specifications

Performance	Capacity		
	240 GB	480 GB	960 GB
<b>Sequential Read* (MB/s)</b>	2,435	2,660	2,610
<b>Sequential Write* (MB/s)</b>	1,040	2,085	2,260
<b>Random Read IOPS** (4K)</b>	187,000	345,000	340,000
<b>Random Write IOPS** (4K)</b>	70,000	134,000	172,000

Note:

Results may differ from various flash configurations or host system setting.

\*Sequential performance is based on CrystalDiskMark 5.2.1 with file size 1,000MB.

\*\*Random performance measured using IOMeter with Queue Depth 64.

### 4.3 Environmental Specifications

Environmental specifications of PV310-M280 are shown in Table 4-3.

**Table 4-3** Environmental Specifications

Item	Specifications
Operating temp.	0°C to 70°C (Standard); -40°C to 85°C (Wide)
Non-operating temp.	-40°C to 100°C
Operating vibration	7.69 GRMS, 20~2000 Hz/random (compliant with MIL-STD-810G)
Non-operating vibration	4.02 GRMS, 15~2000 Hz/random (compliant with MIL-STD-810G)
Operating shock	50(G)/11ms/half sine (compliant with MIL-STD-202G)
Non-operating shock	1,500(G)/0.5(ms)/half sine (compliant with MIL-STD-883K)

Note: Shock and Vibration specifications are subject to change without notice.

## 4.4 Mean Time Between Failures (MTBF)

Mean Time Between Failures (MTBF) is predicted based on reliability data for the individual components in PV310-M280. The prediction result for PV310-M280 is more than 3,000,000 hours.

Note: The MTBF is predicated and calculated based on “Telcordia Technologies Special Report, SR-332, Issue 2” method.

## 4.5 Certification and Compliance

PV310-M280 complies with the following standards:

- CE
- FCC
- RoHS

## 4.6 Endurance

The endurance of a storage device is predicted by Drive Writes Per Day based on several factors related to usage, such as the amount of data written into the drive, block management conditions, and daily workload for the drive. Thus, key factors, such as Write Amplifications and the number of P/E cycles, can influence the lifespan of the drive.

**Table 4-4** Drive Writes Per Day

Capacity	Drive Writes Per Day
240 GB	3.91
480 GB	3.88
960 GB	3.37

Note:

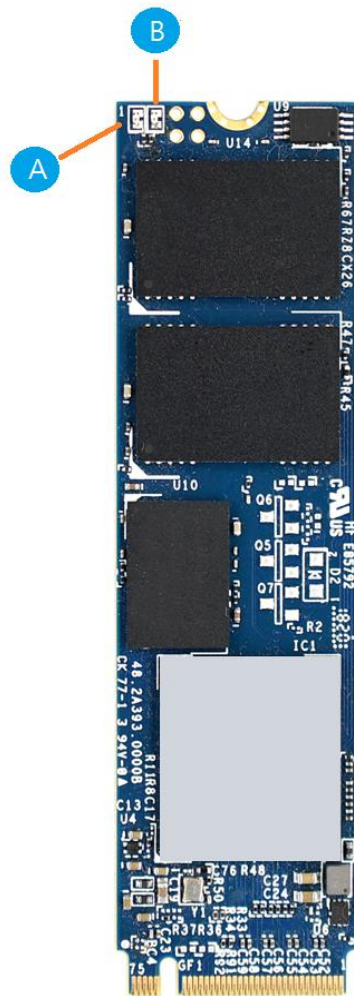
- This estimation complies with JEDEC JESD-219, enterprise endurance workload of random data with payload size distribution.
- Flash vendor guaranteed 3D NAND TLC P/E cycle: 3K
- WAF may vary from capacity, flash configurations and writing behavior on each platform.
- 1 Terabyte = 1,024GB
- DWPD (Drive Writes Per Day) is calculated based on the number of times that user overwrites the entire capacity of an SSD per day of its lifetime during the warranty period. (3D NAND TLC warranty: 2 years)

## 4.7 LED Indicator Behavior

The behavior of the PV310-M280 LED indicators is described in Table 4-5.

**Table 4-5** LED Behavior

Location	LED	Color	Description
LED A	DAS	Red	LED blinks when the drive is being accessed
LED B	PHY	Green	LED blinks when PHY is connected



## 5. Flash Management

### 5.1 Error Correction/Detection

PV310-M280 implements a hardware ECC scheme, based on the Low Density Parity Check (LDPC). LDPC is a class of linear block error correcting code which has apparent coding gain over BCH code because LDPC code includes both hard decoding and soft decoding algorithms. With the error rate decreasing, LDPC can extend SSD endurance and increase data reliability while reading raw data inside a flash chip.

### 5.2 Bad Block Management

Bad blocks are blocks that include one or more invalid bits, and their reliability is not guaranteed. Blocks that are identified and marked as bad by the manufacturer are referred to as “Initial Bad Blocks”. Bad blocks that are developed during the lifespan of the flash are named “Later Bad Blocks”. Apacer implements an efficient bad block management algorithm to detect the factory-produced bad blocks and manages any bad blocks that appear with use. This practice further prevents data being stored into bad blocks and improves the data reliability.

### 5.3 Global Wear Leveling

Flash memory devices differ from Hard Disk Drives (HDDs) in terms of how blocks are utilized. For HDDs, when a change is made to stored data, like erase or update, the controller mechanism on HDDs will perform overwrites on blocks. Unlike HDDs, flash blocks cannot be overwritten and each P/E cycle wears down the lifespan of blocks gradually. Repeatedly program/erase cycles performed on the same memory cells will eventually cause some blocks to age faster than others. This would bring flash storages to their end of service term sooner. Global wear leveling is an important mechanism that levels out the wearing of all blocks so that the wearing-down of all blocks can be almost evenly distributed. This will increase the lifespan of SSDs.

### 5.4 Power Failure Management

Power Failure Management plays a crucial role when power supply becomes unstable. Power disruption may occur when users are storing data into the SSD, leading to instability in the drive. However, with Power Failure Management, a firmware protection mechanism will be activated to scan pages and blocks once power is resumed. Valid data will be transferred to new blocks for merging and the mapping table will be rebuilt. Therefore, data reliability can be reinforced, preventing damage to data stored in the NAND Flash.

Note: The controller unit of this product model is designed with a DRAM as a write cache for improved performance and data efficiency. Though unlikely to happen in most cases, the data cached in the volatile DRAM might be potentially affected if a sudden power loss takes place before the cached data is flushed into non-volatile NAND flash memory.

## 5.5 Flash Translation Layer – Page Mapping

Page mapping is an advanced flash management technology whose essence lies in the ability to gather data, distribute the data into flash pages automatically, and then schedule the data to be evenly written. Page-level mapping uses one page as the unit of mapping. The most important characteristic is that each logical page can be mapped to any physical page on the flash memory device. This mapping algorithm allows different sizes of data to be written to a block as if the data is written to a data pool and it does not need to take extra operations to process a write command. Thus, page mapping is adopted to increase random access speed and improve SSD lifespan, reduce block erase frequency, and achieve optimized performance and lifespan.

## 5.6 TRIM

TRIM is a feature which helps improve the read/write performance and speed of solid-state drives (SSD). Unlike hard disk drives (HDD), SSDs are not able to overwrite existing data, so the available space gradually becomes smaller with each use. With the TRIM command, the operating system can inform the SSD which blocks of data are no longer in use and can be removed permanently. Thus, the SSD will perform the erase action, which prevents unused data from occupying blocks all the time.

## 5.7 Hyper Cache Technology

Apacer proprietary Hyper Cache technology uses a portion of the available capacity as SLC (1bit-per-cell) NAND flash memory, called Hyper cache mode. When data is written to SSD, the firmware will direct the data to Hyper Cache mode, providing excellent performance to handle various scenarios in industrial use.

## 5.8 Over-Provisioning

Over-Provisioning (OP) is a certain portion of the SSD capacity exclusively for increasing Garbage Collection (GC) efficiency, especially when the SSD is filled to full capacity or performs a heavy mixed-random workload. OP has the advantages of providing extended life expectancy, reliable data integrity, and high sustained write performance.

## 5.9 DataRAID™

Apacer's DataRAID algorithm applies an additional level of protection and error-checking. Using this algorithm, a certain amount of space is given over to aggregating and resaving the existing parity data used for error checking. So, in the event that data becomes corrupted, the parity data can be compared to the existing uncorrupted data and the content of the corrupted data can be rebuilt.

## 5.10 NVMe Secure Erase

NVMe Secure Erase is an NVMe drive sanitize command currently embedded in most of the storage drives. Defined in NVMe specifications, NVMe Secure Erase is part of Format NVM command that allows storage drives to erase all user data areas. The erase process usually runs on the firmware level as most of the NVMe-based storage media currently in the market are built-in with this command. NVMe Secure Erase can securely wipe out the user data in the drive and protects it from malicious attack.

## 6. Security & Reliability Features

### 6.1 Thermal Sensor

Apacer Thermal Sensor is a digital temperature sensor with serial interface. By using designated pins for transmission, storage device owners are able to read temperature data.

### 6.2 Thermal Management Technique

Thermal management technique can monitor the temperature of the SSD equipped with a built-in thermal sensor via S.M.A.R.T. commands. This method can ensure the temperature of the device stays within temperature limits by drive throttling, i.e. reducing the speed of the drive when the device temperature reaches the threshold level, so as to prevent overheating, guarantee data reliability, and prolong product lifespan. When the temperature exceeds the maximum threshold level, thermal throttling will be triggered to reduce performance step by step to prevent hardware components from being damaged. Performance is only permitted to drop to the extent necessary for recovering a stable temperature to cool down the device's temperature. Once the temperature decreases to the minimum threshold value, transfer speeds will rise back to its optimum performance level.

### 6.3 End-to-End Data Protection

End-to-End Data Protection is a feature implemented in Apacer SSD products that extends error control to cover the entire path from the host computer to the drive and back, and that ensures data integrity at multiple points in the path to enable reliable delivery of data transfers. Unlike ECC which does not exhibit the ability to determine the occurrence of errors throughout the process of data transmission, End-to-End Data Protection allows SSD controller to identify an error created anywhere in the path and report the error to the host computer before it is written to the drive. This error-checking and error-reporting mechanism therefore guarantees the trustworthiness and reliability of the SSD.

### 6.4 Advanced Encryption Standard

Advanced Encryption Standard (AES) is a specification for the encryption of electronic data. AES has been adopted by the U.S. government since 2001 to protect classified information and is now widely implemented in embedded computing applications. The AES algorithm used in software and hardware is symmetric so that encrypting/decrypting requires the same encryption key. Without the key, the encrypted data is inaccessible to ensure information security.

Notably in flash memory applications, AES 256-bit hardware encryption is the mainstream to protect sensitive or confidential data. The hardware encryption provides better performance, reliability, and security than software encryption. It uses a dedicated processor, which is built inside the controller, to process the encryption and decryption. This enormously shortens the processing time and makes it efficient.

## 6.5 TCG Opal (optional)

Developed by the Trusted Computing Group (TCG), an organization whose members work together to formulate industry standards, Opal is a set of security specifications used for applying hardware-based encryption to storage devices.

Hardware encryption has many advantages. First of all, it transfers the computational load of the encryption process to dedicated processors, reducing the stress on the host system's CPU. In addition, storage devices complying with Opal specifications are self-encryption devices. Opal specifications also feature boot authentication. When the drive is being accessed, the shadow MBR will request the drive password at boot. The drive will only unlock and decrypt if the correct password is supplied. The other feature is LBA-specific permissions. Users are assigned different permissions for LBA ranges created by the device administrator. Each LBA range is password-protected and can only be accessed by users with the correct key to perform permitted actions (read/write/erase).

## 6.6 CoreGlacier™

In many applications, SSDs are subject to challenging conditions. If the working environment is already hot, and the SSD's operation causes it to increase in temperature as well, the result could be damage to the hardware or corrupted data. In cases like this, leading industrial manufacturers know to turn to Apacer. Apacer developed CoreGlacier, a heatsink that distributes dissipation in isolated components with no thermal diffusion, to prevent heat-related damage from occurring.

## 7. Software Interface

### 7.1 Command Set

Table 7-1 summarizes the commands supported by PV310-M280.

**Table 7-1** Admin Commands

Opcode	Command Description
00h	Delete I/O Submission Queue
01h	Create I/O Submission Queue
02h	Get Log Page
04h	Delete I/O Completion Queue
05h	Create I/O Completion Queue
06h	Identify
08h	Abort
09h	Set Features
0Ah	Get Features
0Ch	Asynchronous Event Request
10h	Firmware Activate
11h	Firmware Image Download
14h	Device Self-test

**Table 7-2** Admin Commands – NVM Command Set Specific

Opcode	Command Description
80h	Format NVM
81h	Security Send
82h	Security Receive
84h	Sanitize

**Table 7-3** NVM Commands

Opcode	Command Description
00h	Flush
01h	Write
02h	Read
04h	Write Uncorrectable
05h	Compare
08h	Write Zeroes
09h	Dataset Management

## 7.2 S.M.A.R.T.

SMART, an acronym for Self-Monitoring, Analysis and Reporting Technology, is an open standard that allows a hard disk drive to automatically detect its health and report potential failures. When a failure is recorded by SMART, users can choose to replace the drive to prevent unexpected outage or data loss. Moreover, SMART can inform users of impending failures while there is still time to perform proactive actions, such as copy data to another device.

**Table 7-4 SMART (02h)**

Byte	Length	Description
0	1	Critical Warning
1-2	2	Composite Temperature
3	1	Available Spare
4	1	Available Spare Threshold
5	1	Percentage Used
6-31	26	Reserved
32-47	16	Data Units Read
48-63	16	Data Units Written
64-79	16	Host Read Commands
80-95	16	Host Write Commands
96-111	16	Controller Busy Time
112-127	16	Power Cycles
128-143	16	Power On Hours
144-159	16	Unsafe Shutdowns
160-175	16	Media And Data Integrity Errors
176-191	16	Number Of Error Information Log Entries
192-195	4	Warning Composite Temperature Time
196-199	4	Critical Composite Temperature Time
200-201	2	Temperature Sensor 1
202-203	2	Temperature Sensor 2
204-205	2	Temperature Sensor 3
206-207	2	Temperature Sensor 4
208-209	2	Temperature Sensor 5
210-211	2	Temperature Sensor 6
212-213	2	Temperature Sensor 7
214-215	2	Temperature Sensor 8
216-511	296	Reserved

**Table 7-5 SMART (C0h)**

Byte	Length	Description
0-255	256	Reserved
256-257	2	SSD Protect Mode
258-261	4	ECC Fail Count
262-273	12	Reserved
274-277	4	Total Later Bad Block Count
278-281	4	Max Erase Count
282-285	4	Average Erase Count
286-289	4	Program Fail Count
290-293	4	Erase Fail Count
294-301	8	Flash Write Sector
302-511	210	Reserved

## 8. Electrical Specifications

### 8.1 Operating Voltage

Table 8-1 lists the supply voltage for PV310-M280.

**Table 8-1** Operating Range

Item	Range
Supply Voltage	3.3V $\pm$ 5%

### 8.2 Power Consumption

Table 8-2 lists the power consumption for PV310-M280.

**Table 8-2** Power Consumption

Mode \ Capacity	240 GB	480 GB	960 GB
Active (mA)	1,590	1,635	1,725
Idle (mA)	245	250	250

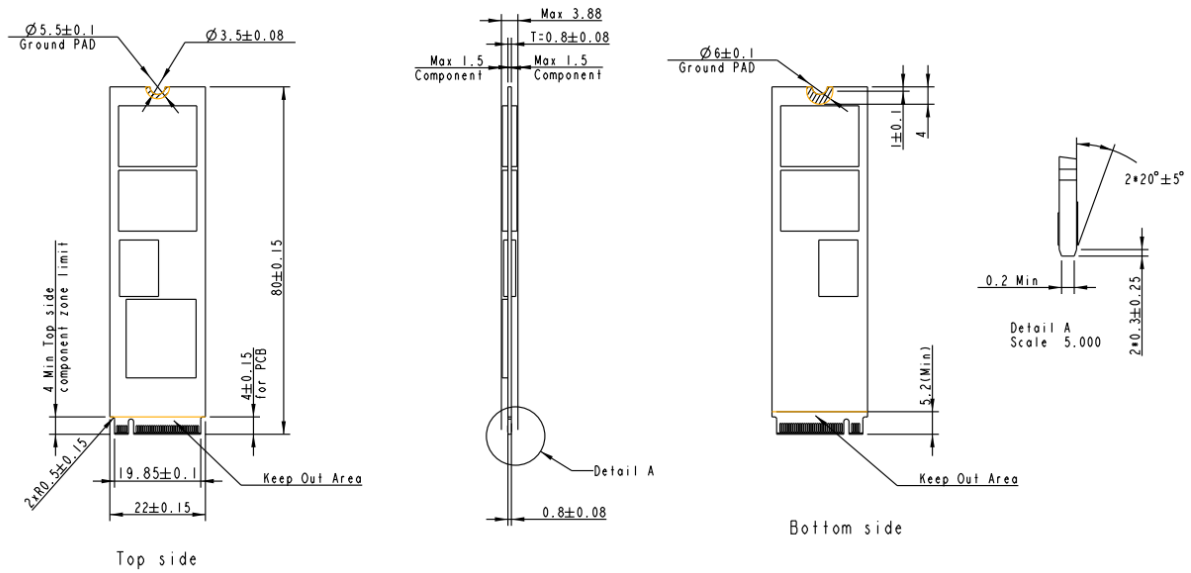
Note:

\*All values are typical and may vary depending on flash configurations or host system settings.

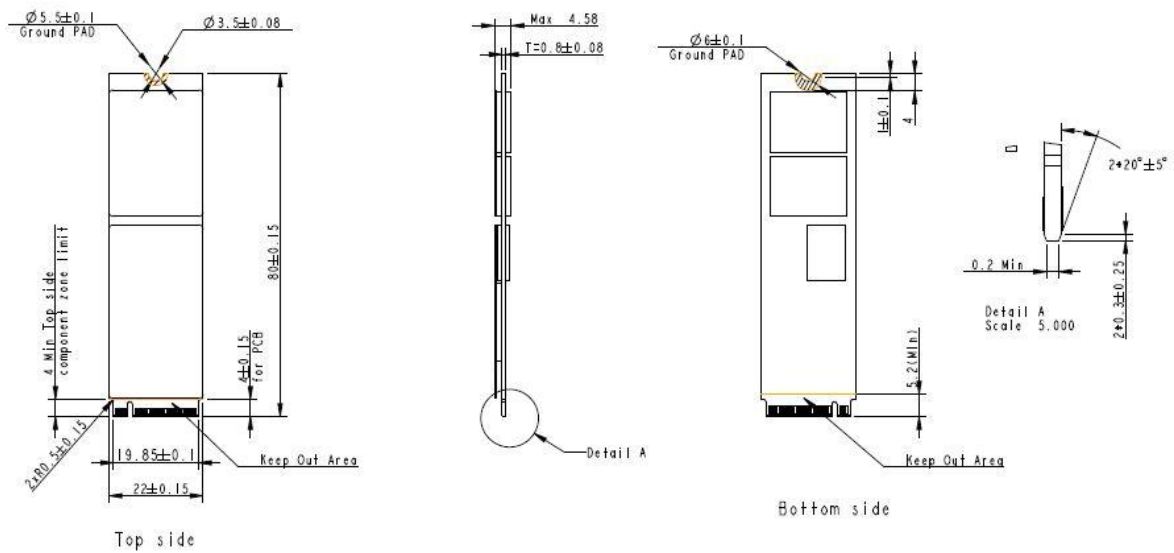
\*\*Active power is an average power measurement performed using CrystalDiskMark with 128KB sequential read/write transfers.

## 9. Physical Characteristics

### 9.1 Standard Temperature



### 9.2 Wide Temperature



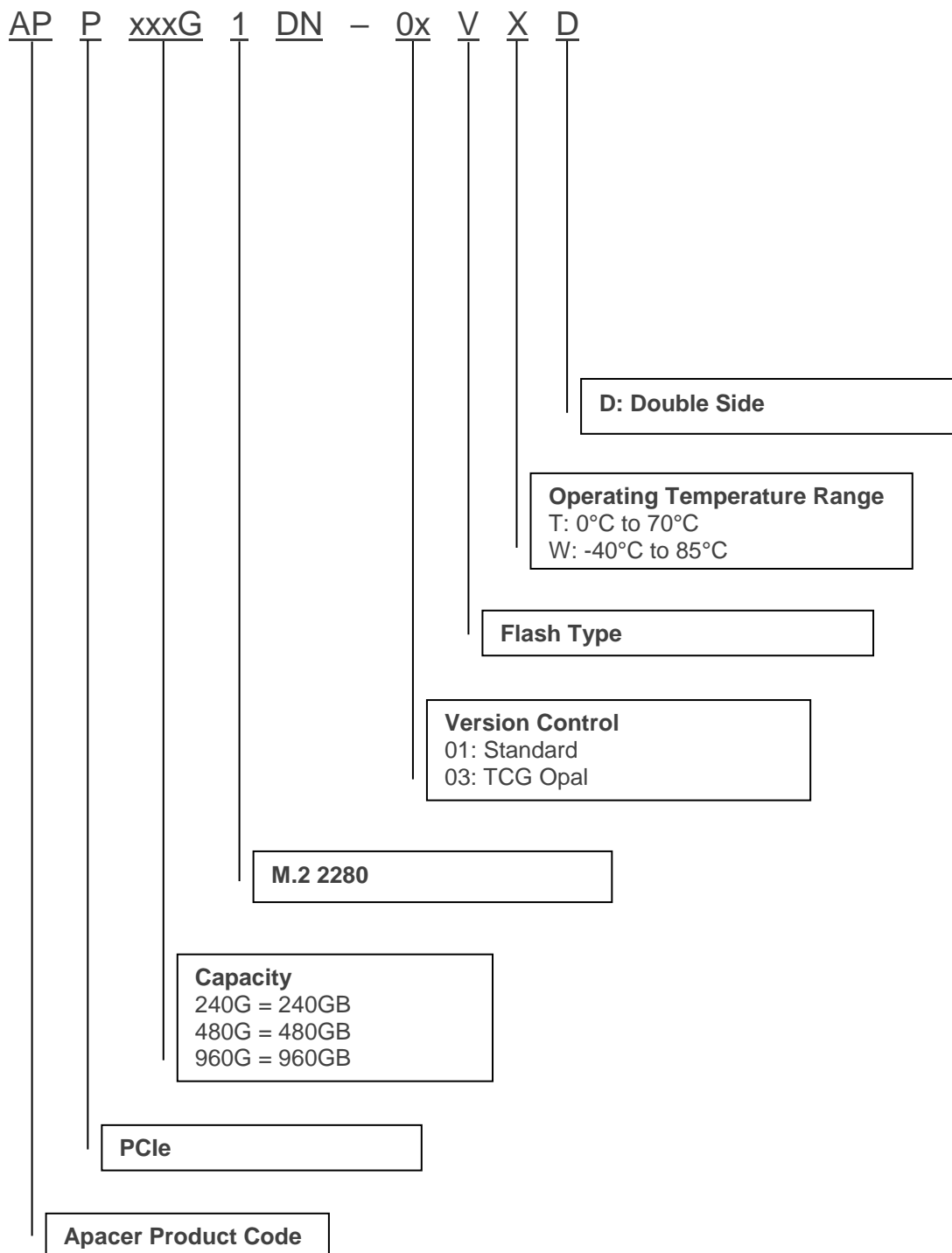
### 9.3 Net Weight

Table 9-1 Net Weight

Standard Temperature	
Capacity	Net Weight (g ± 5%)
240GB	7.92
480GB	7.92
960GB	7.92
Wide Temperature	
Capacity	Net Weight (g ± 5%)
240GB	10.10
480GB	10.10
960GB	10.10

## 10. Product Ordering Information

### 10.1 Product Code Designations



## 10.2 Valid Combinations

### 10.2.1 Standard

Capacity	Standard Temperature	Wide Temperature
240GB	APP240G1DN-01VTD	APP240G1DC-01VWD
480GB	APP480G1DN-01VTD	APP480G1DC-01VWD
960GB	APP960G1DN-01VTD	APP960G1DC-01VWD

### 10.2.2 TCG Opal (optional)

Capacity	Standard Temperature	Wide Temperature
240GB	APP240G1DN-03VTD	APP240G1DC-03VWD
480GB	APP480G1DN-03VTD	APP480G1DC-03VWD
960GB	APP960G1DN-03VTD	APP960G1DC-03VWD

**Note:** Valid combinations are those products in mass production or will be in mass production. Consult your Apacer sales representative to confirm availability of valid combinations and to determine availability of new combinations.

## Revision History

Revision	Description	Date
0.1	Preliminary release	2/26/2019
0.2	<ul style="list-style-type: none"> <li>- Updated product photo on the cover page</li> <li>- Added Endurance and LED Indicators for Drive Behavior to Specifications Overview</li> <li>- Added Over-Provisioning to Flash Management on Specifications Overview</li> <li>- Added 4.6 Endurance, 4.7 LED Indicator Behavior and 5.7 Over-Provisioning</li> <li>- Removed wide temperature and DataDefender support</li> </ul>	4/16/2019
0.3	<ul style="list-style-type: none"> <li>- Updated Performance and Power Consumption on Specifications Overview page</li> <li>- Updated read/write performance for 1. General Descriptions</li> <li>- Updated 4.2 Performance and 8.2 Power Consumption</li> <li>- Updated Table 7-5 SMART (C0h)</li> </ul>	5/21/2019
1.0	<ul style="list-style-type: none"> <li>- Completed endurance rating for Endurance on Specifications Overview page and 4.6 Endurance</li> <li>- Added Power Failure Management and DataRAID to Flash Management on Specifications Overview page</li> <li>- Added 5.4 Power Failure Management and 5.9 DataRAID</li> </ul>	6/12/2019
1.1	Removed 120GB support	6/20/2019
1.2	<ul style="list-style-type: none"> <li>- Updated interface bust read/write from 2GB/sec to 4GB/sec at Performance on Specifications Overview page</li> <li>- Updated storage temperature range from -40°C to 100°C to -40°C to 85°C</li> </ul>	8/29/2019
1.3	Updated the note regarding random performance measuring method at 4.2 Performance	9/4/2019
1.4	<ul style="list-style-type: none"> <li>- Added AES 256-bit hardware encryption to Security section on Specifications Overview page</li> <li>- Updated technology description for 5.4 Power Failure Management</li> <li>- Added 6.4 Advanced Encryption Standard</li> </ul>	9/6/2019
1.5	<ul style="list-style-type: none"> <li>- Added NVMe Secure Erase to Flash Management on Specifications Overview page</li> <li>- Added 5.10 NVMe Secure Erase</li> </ul>	10/14/2019
1.6	<ul style="list-style-type: none"> <li>- Added product photo to the cover page</li> <li>- Added CoreGlacier and wide temperature support</li> <li>- Updated form factor, dimensions and net weight on Specifications Overview page</li> </ul>	12/3/2019

Revision	Description	Date
	<ul style="list-style-type: none"> <li>- Updated shock specifications at 4.3 Environmental Specifications</li> <li>- Updated 9. Physical Characteristics by adding the mechanical spec and net weight information for wide temperature model</li> <li>- Updated 10. Product Ordering Information by adding product code and valid combinations for wide temperature model</li> </ul>	
1.7	Modified total bytes at Table 4-1 Capacity Specifications	2/6/2020
1.8	Updated the mechanical spec for wide temperature model at 9.2 Wide Temperature	3/31/2020
1.9	<ul style="list-style-type: none"> <li>- Added a paragraph regarding security to 1. General Descriptions</li> <li>- Removed cylinders, heads and sector information from Table 4.1 Capacity Specifications and changed max LBA to total LBA</li> <li>- Added TCG Opal support by adding TCG Opal to Security on Specifications Overview page and 6.5 TCG Opal</li> <li>- Modified MTBF from &gt;1,000,000 hours to &gt;3,000,000 hours</li> <li>- Updated endurance rating at Endurance on Specifications Overview page and 4.6 Endurance</li> <li>- Modified the description of 5.10 NVMe Secure Erase by changing Security Feature Set to Format NVM command</li> <li>- Added 14h to Table 7-1 and 84h to Table 7-2</li> <li>- Capitalized only the first letter for commands at 7.1 Software Interface</li> <li>- Updated 10. Product Ordering Information by adding version control code 03</li> </ul>	5/12/2020

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